PCA9515

I²C-bus repeater

Rev. 09 — 23 April 2009 **Product data sheet**

1. General description

The PCA9515 is a BiCMOS integrated circuit intended for application in I²C-bus and SMBus systems.

While retaining all the operating modes and features of the I²C-bus system, it permits extension of the I²C-bus by buffering both the data (SDAn) and the clock (SCLn) lines, thus enabling two buses of 400 pF.

The I²C-bus capacitance limit of 400 pF restricts the number of devices and bus length. Using the PCA9515 enables the system designer to isolate two halves of a bus, thus more devices or longer length can be accommodated. It can also be used to run two buses, one at 5 V and the other at 3.3 V or a 400 kHz and 100 kHz bus, where the 100 kHz bus is isolated when 400 kHz operation of the other is required.

Two or more PCA9515**s cannot be put in series.** The PCA9515 design does not allow this configuration. Since there is no direction pin, slightly different 'legal' low voltage levels are used to avoid lock-up conditions between the input and the output. A 'regular low' applied at the input of a PCA9515 will be propagated as a 'buffered low' with a slightly higher value. When this 'buffered low' is applied to another PCA9515, PCA9516A, or PCA9518A in series, the second PCA9515, PCA9516A, or PCA9518A will not recognize it as a 'regular low' and will not propagate it as a 'buffered low' again. The PCA9510A/9511A/9513A/9514A and PCA9512A cannot be used in series with the PCA9515, PCA9516A, or PCA9518A but can be used in series with themselves since they use shifting instead of static offsets to avoid lock-up conditions.

The PCA9515 SCLn/SDAn C_i is about 200 pF versus the normal < 10 pF when V_{CC} = 0 V. The newer PCA9515A should be used in applications where power is secured to the repeater but an active bus remains on either set of SCLn/SDAn pins to prevent this increase in bus loading. Additionally, the PCA9515A has a wider voltage range of 2.3 V to 3.6 V and can be used in applications with lower voltage supply constraints.

2. Features

- 2 channel, bidirectional buffer
- I²C-bus and SMBus compatible
- Active HIGH repeater enable input
- Open-drain input/outputs
- Lock-up free operation
- Supports arbitration and clock stretching across the repeater
- Accommodates Standard-mode and Fast-mode I²C-bus devices and multiple masters
- Powered-off high-impedance I²C-bus pins
- Operating supply voltage range of 3.0 V to 3.6 V

founded by Philips

- 5.5 V tolerant I²C-bus (SCLn, SDAn) and enable (EN) pins
- 0 Hz to 400 kHz clock frequency[1]
- ESD protection exceeds 2000 V HBM per JESD22-A114, 200 V MM per JESD22-A115, and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- Packages offered: SO8 and TSSOP8 (MSOP8)

3. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
PCA9515D	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1
PCA9515DP	TSSOP8[1]	plastic thin shrink small outline package; 8 leads; body width 3 mm	SOT505-1

[1] Also known as MSOP8.

3.1 Ordering options

Table 2. Ordering options

Type number	Topside mark	Temperature range
PCA9515D	PCA9515	T_{amb} = –40 °C to +85 °C
PCA9515DP	9515	T_{amb} = –40 °C to +85 °C

4. Block diagram

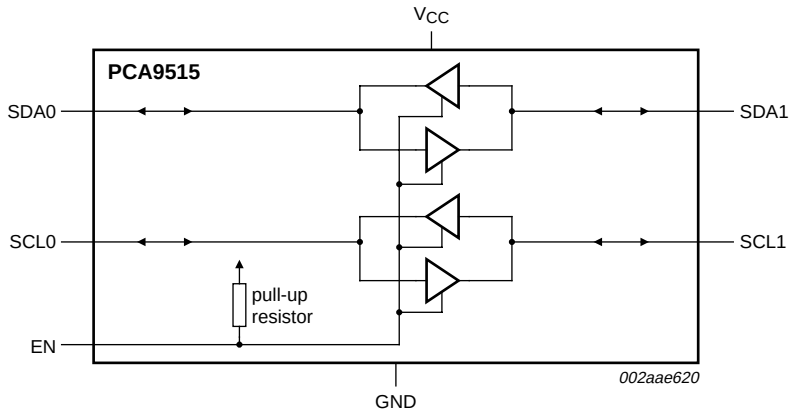


Fig 1. Block diagram of PCA9515

The output pull-down of each internal buffer is set for approximately 0.5 V, while the input threshold of each internal buffer is set about 0.07 V lower, when the output is internally driven LOW. This prevents a lock-up condition from occurring.

1. The maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater.

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5. Pinning information

5.1 Pinning

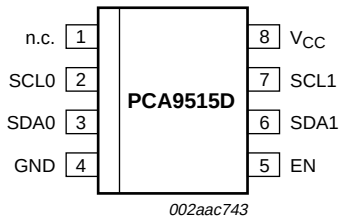


Fig 2. Pin configuration for SO8

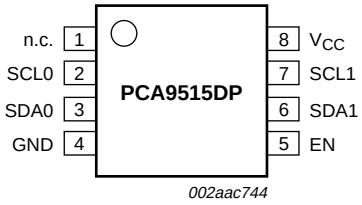


Fig 3. Pin configuration for TSSOP8

5.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
SCL0	2	serial clock bus 0
SDA0	3	serial data bus 0
GND	4	supply ground
EN	5	active HIGH repeater enable input
SDA1	6	serial data bus 1
SCL1	7	serial clock bus 1
V_{CC}	8	supply power

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6. Functional description

The PCA9515 BiCMOS integrated circuit contains two identical buffer circuits which enable I²C-bus and similar bus systems to be extended without degradation of system performance. (Refer to Figure 1 “Block diagram of PCA9515”.)

The PCA9515 BiCMOS integrated circuit contains two bidirectional open-drain buffers specifically designed to support the standard low-level-contention arbitration of the I²C-bus. Except during arbitration or clock stretching, the PCA9515 acts like a pair of non-inverting, open-drain buffers, one for SDA and one for SCL.

6.1 Enable

The EN pin is active HIGH with an internal pull-up and allows the user to select when the repeater is active. This can be used to isolate a badly behaved slave on power-up until after the system power-up reset. It should never change state during an I²C-bus operation because disabling during a bus operation will hang the bus and enabling part way through a bus cycle could confuse the I²C-bus parts being enabled.

The enable pin (EN) should only change state when the global bus and the repeater port are in an idle state to prevent system failures.

6.2 I²C-bus systems

As with the standard I²C-bus system, pull-up resistors are required to provide the logic HIGH levels on the buffered bus. (Standard open-collector configuration of the I²C-bus.) The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. This part is designed to work with Standard-mode and Fast-mode I²C-bus devices in addition to SMBus devices. Standard-mode I²C-bus devices only specify 3 mA output drive; this limits the termination current to 3 mA in a generic I²C-bus system where Standard-mode devices and multiple masters are possible. Under certain conditions, higher termination currents can be used. Please see application note *AN255, “I²C/SMBus Repeaters, Hubs and Expanders”* for additional information on sizing resistors and precautions when using more than one PCA9515 in a system or using the PCA9515 in conjunction with the P82B96.

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7. Application design-in information

A typical application is shown in Figure 4. In this example, the system master is running on a 3.3 V I²C-bus while the slave is connected to a 5 V bus. Both buses run at 100 kHz unless the slave bus is isolated and then the master bus can run at 400 kHz. Master devices can be placed on either bus.

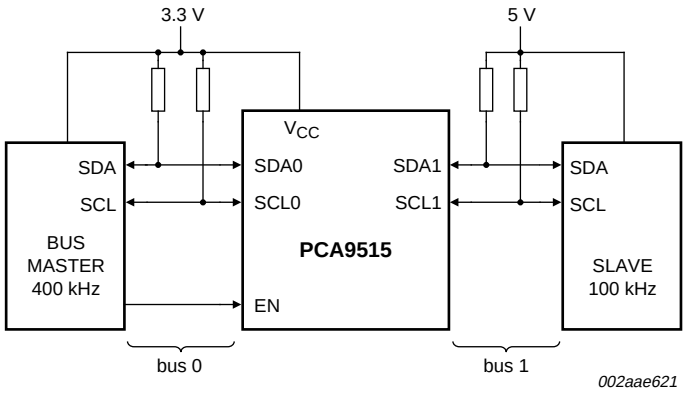


Fig 4. Typical application

The PCA9515 is 5 V tolerant so it does not require any additional circuitry to translate between the different bus voltages.

When one side of the PCA9515 is pulled LOW by a device on the I²C-bus, a CMOS hysteresis type input detects the falling edge and causes an internal driver on the other side to turn on, thus causing the other side to also go LOW. The side driven LOW by the PCA9515 will typically be at V_{OL} = 0.5 V.

In order to illustrate what would be seen in a typical application, refer to Figure 5 and Figure 6. If the bus master in Figure 4 were to write to the slave through the PCA9515, we would see the waveform shown in Figure 5 on Bus 0. This looks like a normal I²C-bus transmission until the falling edge of the 8th clock pulse. At that point, the master releases the data line (SDA) while the slave pulls it LOW through the PCA9515. Because the V_{OL} of the PCA9515 is typically around 0.5 V, a step in the SDA will be seen. After the master has transmitted the 9th clock pulse, the slave releases the data line.

On the Bus 1 side of the PCA9515, the clock and data lines would have a positive offset from ground equal to the V_{OL} of the PCA9515. After the 8th clock pulse, the data line will be pulled to the V_{OL} of the slave device that is very close to ground in our example.

It is important to note that any arbitration or clock stretching events on Bus 1 require that the V_{OL} of the devices on Bus 1 be 70 mV below the V_{OL} of the PCA9515 (see V_{OL}–V_{ILc} in Section 9 “Static characteristics”) to be recognized by the PCA9515 and then transmitted to Bus 0.

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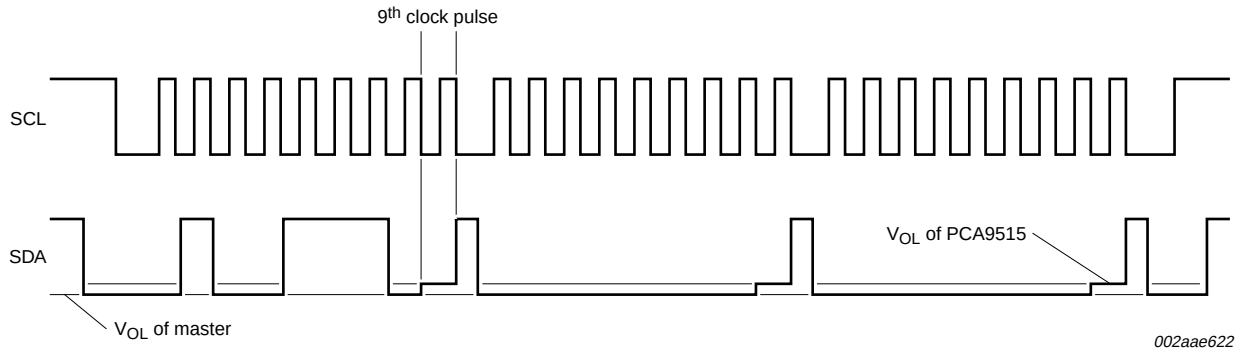


Fig 5. Bus 0 waveform

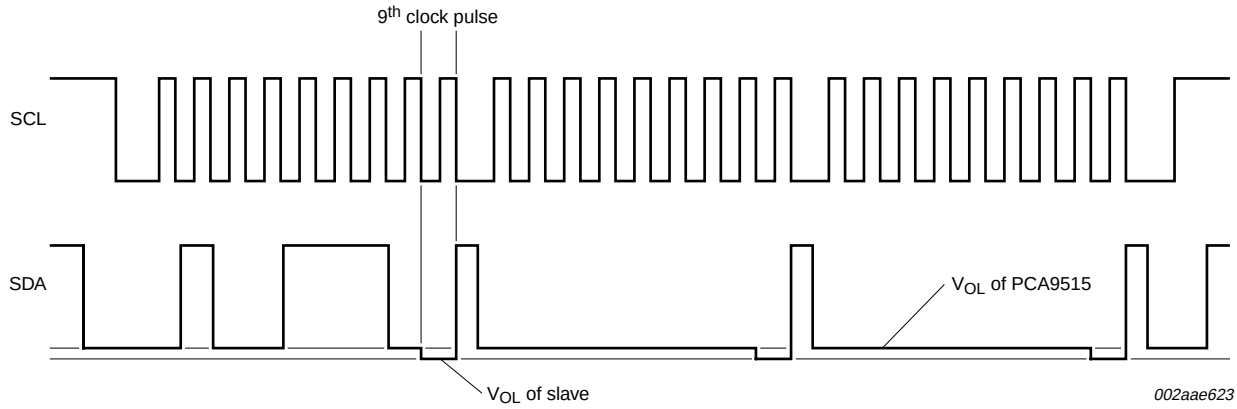


Fig 6. Bus 1 waveform

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).
Voltages with respect to GND.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		–0.5	+7	V
V_{bus}	voltage range I^2C-bus	SCL or SDA	–0.5	+7	V
I	DC current	any pin	-	50	mA
P_{tot}	total power dissipation		-	100	mW
T_{stg}	storage temperature		–55	+125	°C
T_{amb}	ambient temperature	operating	–40	+85	°C

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9. Static characteristics

Table 5. Static characteristics

V_{CC} = 3.0 V to 3.6 V; GND = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supplies						
V_{CC}	supply voltage		3.0	3.3	3.6	V
I_{CCH}	HIGH-level supply current	both channels HIGH; V_{CC} = 3.6 V; SDAn = SCLn = V_{CC}	-	2.3	5	mA
I_{CCL}	LOW-level supply current	both channels LOW; V_{CC} = 3.6 V; one SDA and one SCL = GND, other SDA and SCL open	-	2.3	5	mA
I_{CCLc}	contention LOW-level supply current	V_{CC} = 3.6 V; SDAn = SCLn = GND	-	2.1	5	mA
Input SCLn; input/output SDAn						
V_{IH}	HIGH-level input voltage		$0.7V_{CC}$	-	5.5	V
V_{IL}	LOW-level input voltage	[1]	−0.5	-	$+0.3V_{CC}$	V
V_{ILc}	contention LOW-level input voltage	[1]	−0.5	-	+0.4	V
V_{IK}	input clamping voltage	I_I = −18 mA	-	-	−1.2	V
I_{LI}	input leakage current	V_I = 3.6 V	−1	-	+1	µA
I_{IL}	LOW-level input current	SDA, SCL; V_I = 0.2 V	-	-	10	µA
V_{OL}	LOW-level output voltage	I_{OL} = 0 mA or 6 mA	0.47	0.52	0.6	V
V_{OL}–V_{ILc}	difference between LOW-level output and LOW-level input voltage contention	guaranteed by design	-	-	70	mV
I_{LOH}	HIGH-level output leakage current	V_O = 3.6 V	-	-	10	µA
C_i	input capacitance	V_I = 3 V or 0 V	-	6	7[2]	pF
Enable input EN						
V_{IL}	LOW-level input voltage		−0.5	-	+0.8	V
V_{IH}	HIGH-level input voltage		2.0	-	5.5	V
I_{IL}	LOW-level input current	EN; V_I = 0.2 V	-	10	30	µA
I_{LI}	input leakage current		−1	-	+1	µA
C_i	input capacitance	V_I = 3.0 V or 0 V	-	6	7	pF

[1] V_{IL} specification is for the first LOW level seen by the SDAn/SCLn lines. V_{ILc} is for the second and subsequent LOW levels seen by the SDAn/SCLn lines.

[2] The SCLn/SDAn C_i is about 200 pF when V_{CC} = 0 V. The PCA9515A should be used in applications where power is secured to the repeater but an active bus remains on either set of SCLn/SDAn pins.

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10. Dynamic characteristics

Table 6. Dynamic characteristics

V_{CC} = 3.0 V to 3.6 V; GND = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	Figure 7		57	98	170	ns
t_{PLH}	LOW to HIGH propagation delay	Figure 7		33	55	78	ns
t_{THL}	HIGH to LOW output transition time	Figure 7		-	67	-	ns
t_{TLH}	LOW to HIGH output transition time	Figure 7	[1]	-	135	-	ns
t_{su}	set-up time	EN to START condition		100	-	-	ns
t_h	hold time	EN after STOP condition		100	-	-	ns

[1] The t_{TLH} transition time is specified with loads of 1.35 kΩ pull-up resistance and 7 pF load capacitance, plus an additional 50 pF load capacitance. Different load resistance and capacitance will alter the RC time constant, thereby changing the propagation delay and transition times.

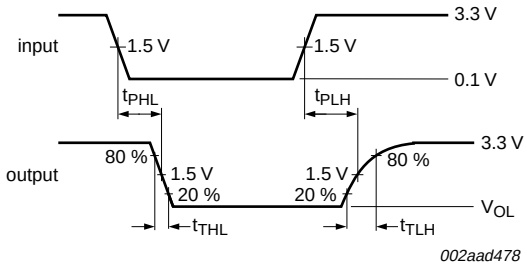
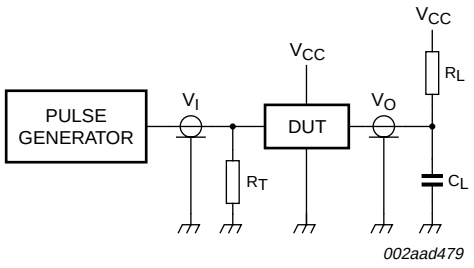


Fig 7. Propagation delay and transition times

11. Test information



R_L = load resistor; 1.35 kΩ.

C_L = load capacitance includes jig and probe capacitance; 7 pF.

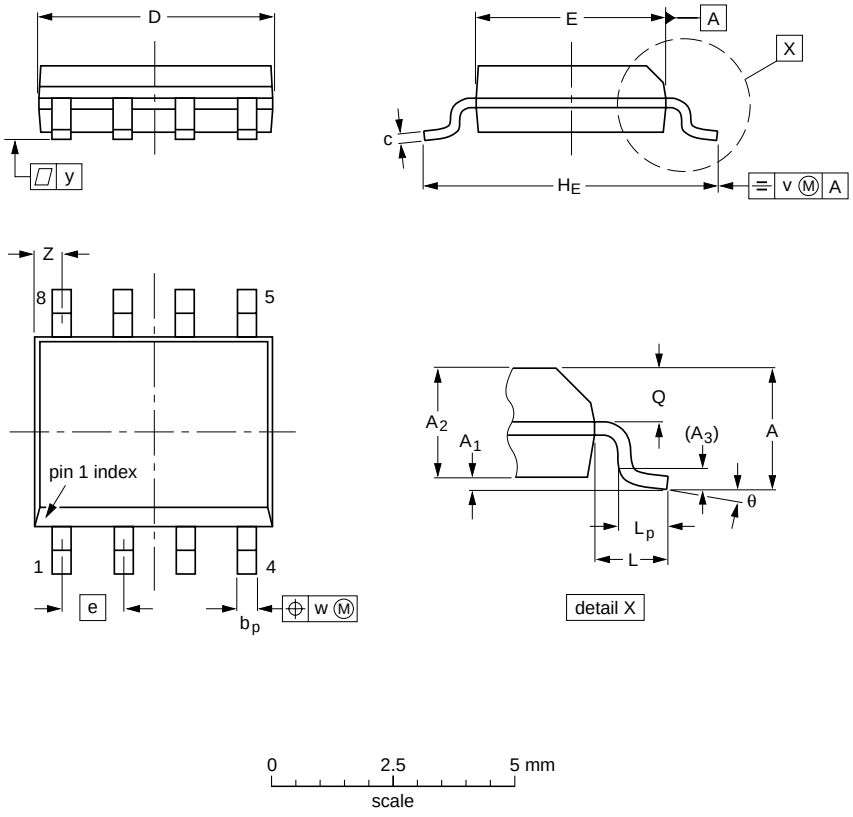
R_T = termination resistance should be equal to Z_o of pulse generators.

Fig 8. Test circuit for open-drain outputs

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12. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

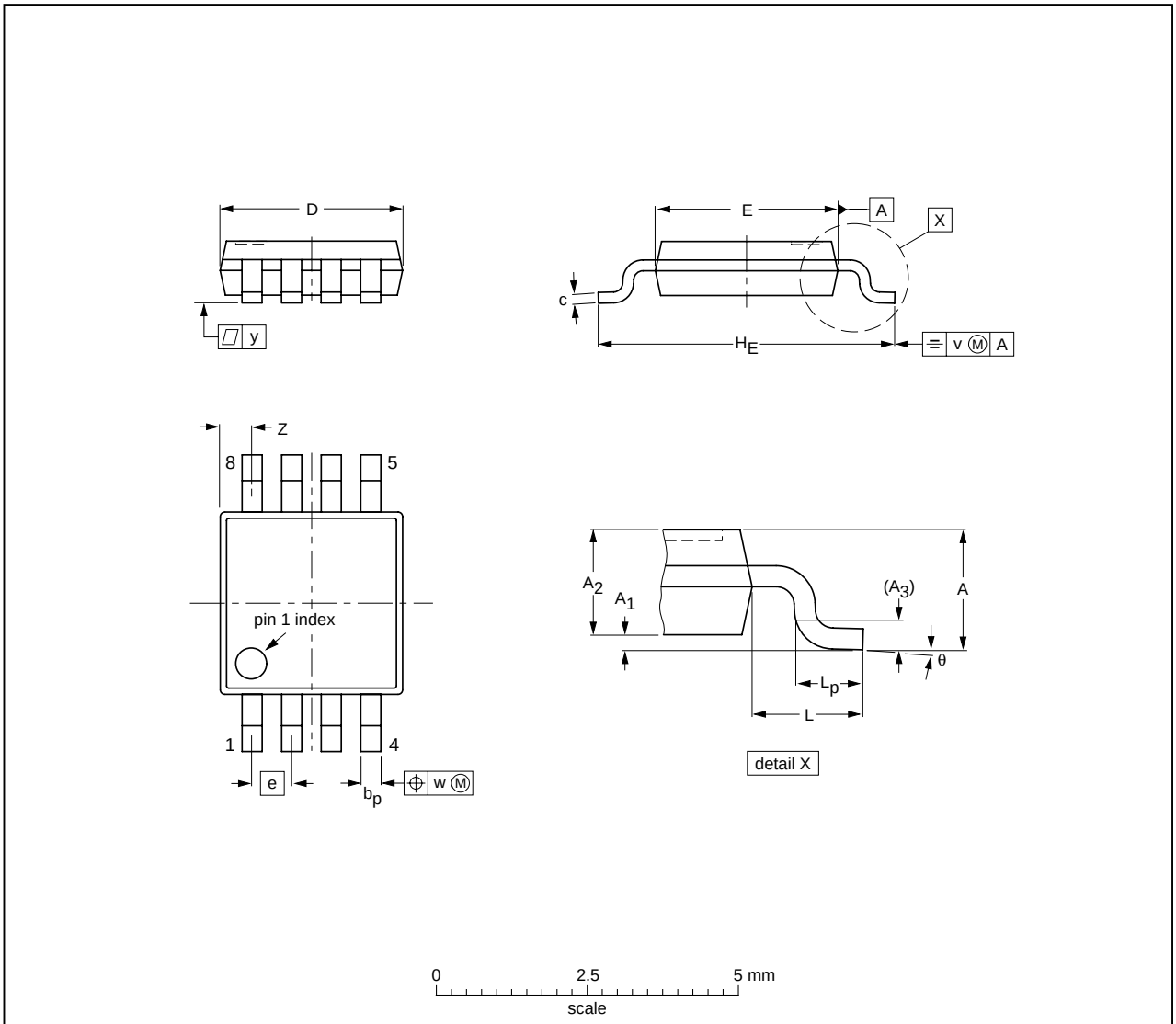
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT96-1	076E03	MS-012				~~99-12-27~~ 03-02-18

Fig 9. Package outline SOT96-1 (SO8)

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TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm **SOT505-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.45 0.25	0.28 0.15	3.1 2.9	3.1 2.9	0.65	5.1 4.7	0.94	0.7 0.4	0.1	0.1	0.1	0.70 0.35	6° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT505-1						~~99-04-09~~ 03-02-18

Fig 10. Package outline SOT505-1 (TSSOP8)

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13. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

13.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

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13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 11) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 7 and 8

Table 7. SnPb eutectic process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

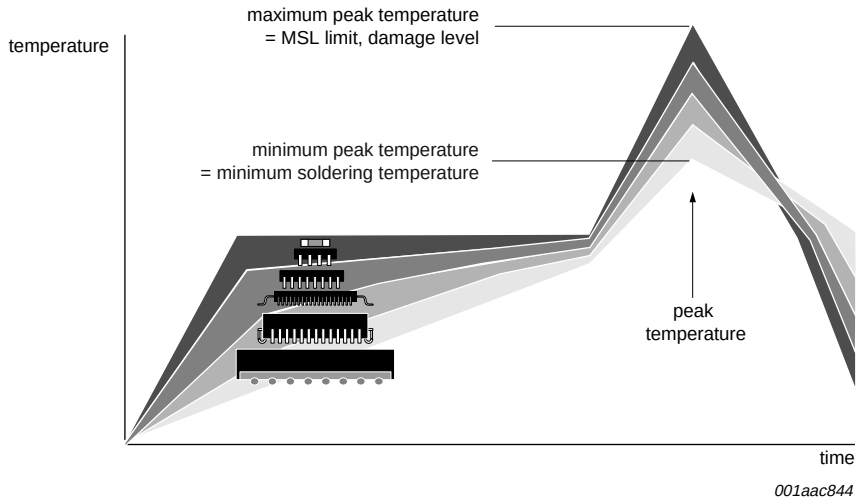
Table 8. Lead-free process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 11.

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MSL: Moisture Sensitivity Level

Fig 11. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

14. Abbreviations

Table 9. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal-Oxide Semiconductor
CDM	Charged-Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
I²C-bus	Inter-Integrated Circuit bus
MM	Machine Model
RC	Resistor-Capacitor network
SMBus	System Management Bus

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15. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9515_9	20090423	Product data sheet	-	PCA9519_8
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 1 “General description”: – 4th paragraph: referenced part type numbers changed from “PCA951x” to “PCA951xA” (excludes PCA9515) – Added new 5th paragraph • Table 5 “Static characteristics”, sub-section “Input SCLn; input/output SDAn”: – Symbol for parameter “input leakage current” changed from “I_I” to “I_{LI}” – Symbol/parameter changed from “I_{OH}, output HIGH level leakage current” to “I_{LOH}, HIGH-level output leakage current • Added soldering information • Added Section 14 “Abbreviations”			
PCA9515_8 (9397 750 14097)	20040929	Product data sheet	-	PCA9515_7
PCA9515_7 (9397 750 12875)	20040624	Product data sheet	-	PCA9515_6
PCA9515_6 (9397 750 12294)	20031110	Product data	853-2223 30410 dated 2003 Oct 03	PCA9515_5
PCA9515_5 (9397 750 09814)	20020513	Product data	853-2223 28185 dated 2002 May 13	PCA9515_4
PCA9515_4 (9397 750 09512)	20020301	Product data	853-2223 27802	PCA9515_3
PCA9515_3 (9397 750 08127)	20010307	Product specification	853-2223 25782	PCA9515_2
PCA9515_2 (9397 750 07852)	20001201	Product specification	853-2223 25138	PCA9515_1
PCA9515_1 (9397 750 07757)	20001113	Product specification	853-2223 25005	-

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16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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